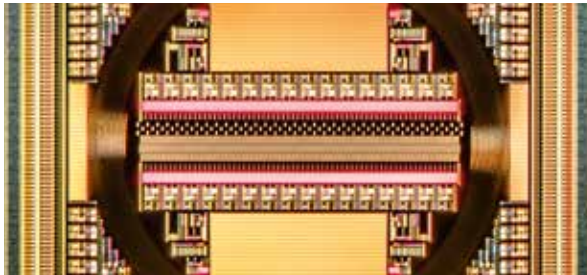


# Highlights

## Infrastructure



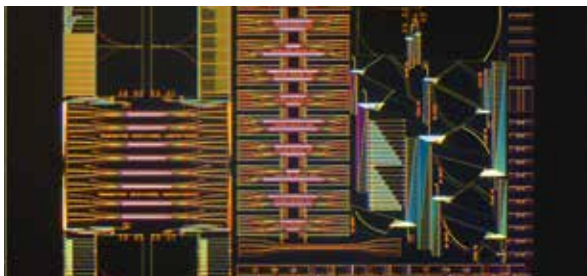
*Chipfilm Patch with ASIC*



*Opto-mix-signal ASIC*



*Membrane wafer for fuel cells on Si MEMS basis*



*Photonic chip*

- 1,400 m<sup>2</sup> cleanroom ISO04
- Complete front- and back-end of line process line with Si epitaxy, deposition, metallization and etching equipment
- GaN-on-Si technology line for 150 and 200 mm wafers (CMOS compatible)
- Mask production line for 6, 9, 12 and 17 inch (430 mm) substrates
- Lithography (i-Line stepper, direct laser writing and direct electron beam writing as well as back and proximity exposure)
- Packaging and interconnection techniques with wafer processing up to 200 mm including back-thinning
- Test and quality assurance environment



**One source  
from idea  
to product**

# IMS CHIPS



We look back on more than 30 years of experience in developing various applications and processes in the field of microelectronics and nano technology for both research and industry. With our modern equipment and a strong network of partners we find solutions for your products and your ideas.

## Competences

- ASIC design and foundry manufacturing
- Bio-medical electronics
- Industry 4.0
- Microsystems
- Image sensors and cameras
- CMOS image sensors
- Non-contact (high) temperature measurement
- Silicon processing
- Hybrid systems-in-foil
- GaN technology
- Silicon photonics
- Membrane processing
- 3D replication masters
- Diffractive and optical components (e. g. CGH)
- Photo masks

## Portfolio



- Qualified individual processes and process chains for silicon, GaN-on-Si and quartz wafers up to 200 mm
- Advanced packing processing for hybrid foil systems with embedded silicon chips
- Processing of 6.9 and 12 inch quartz masks and quartz substrates with a diameter of 430 mm
- Design and manufacture of silicon photonic components
- IECQ and ISO 9001 certification (process certification according to ISO 90001, manufacturers of microchips according to IECQ)

